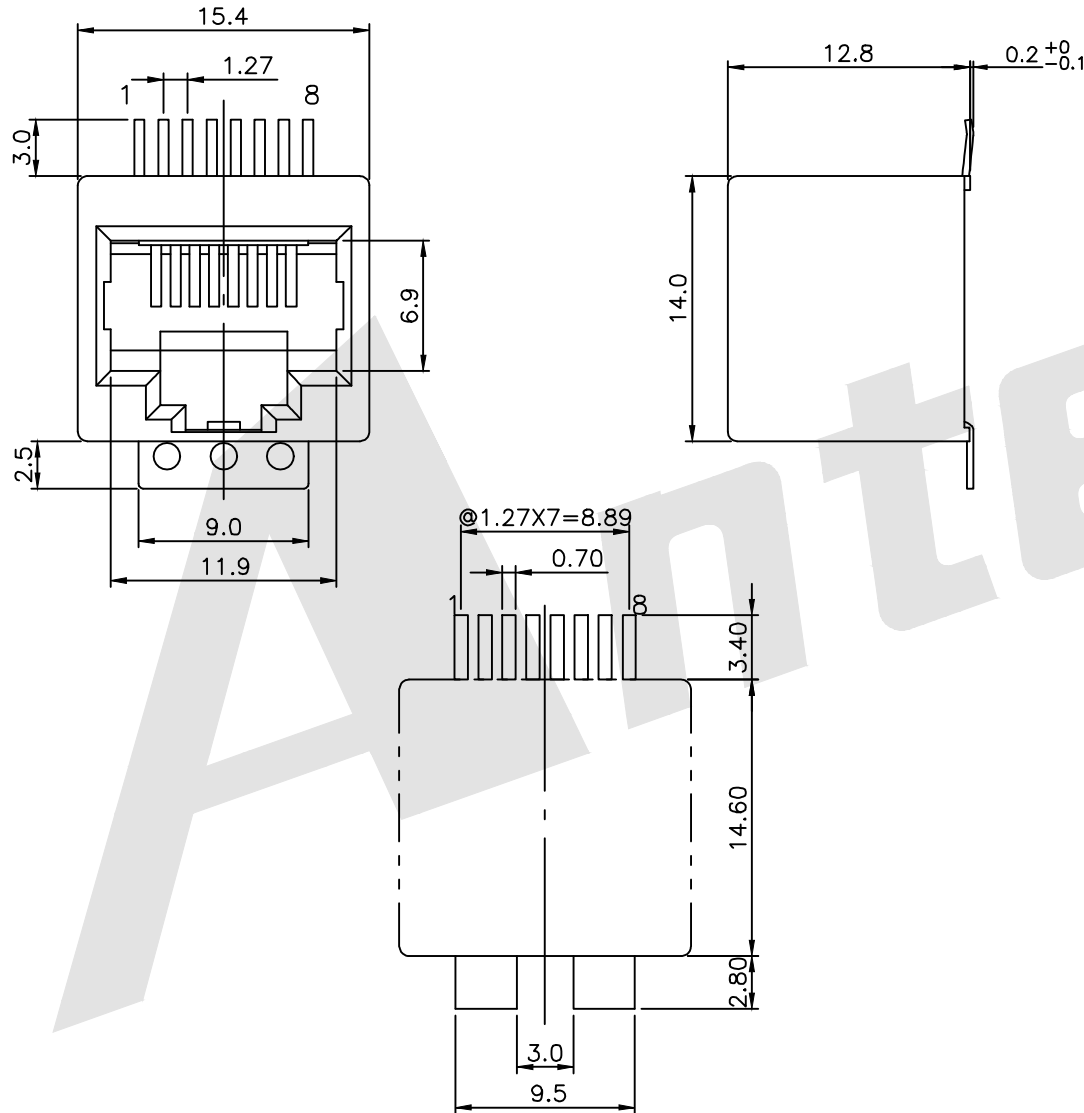


HSF



PCB LAYOUT (COMPONENT SIDE VIEW)

MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL :PHOSPHOR BRONZE $t=0.35\text{mm}$
3. PLATING :SELECTING GOLD PLATING
1u~50u"OVER NICKEL IN CONTACT AREA. 150u" TIN PLATING
OVER NICKEL IN SOLDER AREA.
4. SHIELD :0.2mm THICKNESS COPPER ALLY WITH NICKEL . PLATEL

ELECTRICAL:

1. VOLTAGE PATING :125 VAC RMS.
2. CURRENT PATING :1.5 AMP
3. CONTACT RESISTANCE :30 MILLIOHMS MAX
4. INSULATION RESISTANCE:1000 MEGOHMS MIN @ 500V DC.
5. DIELECTRIC WITHSTANDING RESISTANCE: 1000V AC RMS 60Hz. 1MIN

MECHANICAL:

1. DURRABILITY :750 CYCLES MIN
2. PCB RETENTION PRE-SOLDER :10LB MIN

ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C .
2. OPERATION : -40°C TO +85°C .
3. IR REFLOW SOLDERING TEMPERATURE: 255~265°C (5~10 SECONDS) MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68 SUBPART F.

Order Code:

ATRJ5823 - 8P - 8C - X - A - X

① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating
G0:Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3: 10U" Gold
G4: 15U" Gold
G5: 30U" Gold
SN: Tin

- ⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml
- ⑥ packing:
A: Tray packing
R: Tape & Reel

Unless Otherwise specified tolerance
X. ± 0.35 X.XX: ± 0.20
X.X: ± 0.25 X.XXX: ± 0.15

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018



3rd ANGLE PROJECTION

Antenk® ANTENK ELECTRONICS CO.,LTD
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E-mail:sales@antenk.com

TITLE:
TOP ENTRY SMT PCB JACK 8P

DRAWING NO: ATRJ5823-8P8C-X-A-X

PRODUCT NO: ATRJ5823-8P8C-X-A-X

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		